

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

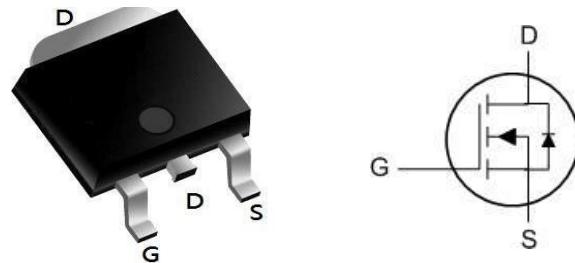
| BVDSS | RDS(on) | ID |
|-------|---------|-----|
| 100V | 32 mΩ | 30A |

Description

The MT30N10 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications .

The MT30N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|---------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 100 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _c =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 30 | A |
| I _D @T _c =100°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 15 | A |
| I _{DM} | Pulsed Drain Current ² | 80 | A |
| EAS | Single Pulse Avalanche Energy ³ | 4.0 | mJ |
| I _{AS} | Avalanche Current | 30 | A |
| P _D @T _c =25°C | Total Power Dissipation ³ | 43.7 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-ambient ¹ | — | 50 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | — | 3.0 | °C/W |

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|--|----------------------|---|------|------|------|------|
| Static Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} = 0V, I _D = 250μA | 100 | - | - | V |
| Gate-body Leakage current | I _{GSS} | V _{DS} = 0V, V _{GS} = ±20V | - | - | ±100 | nA |
| Zero Gate Voltage Drain Current T _J =25°C T _J =100°C | I _{DSS} | V _{DS} =100V, V _{GS} = 0V | - | - | 1 | μA |
| | | | - | - | 100 | |
| Gate-Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250μA | 1.2 | - | 2.5 | V |
| Drain-Source on-Resistance ⁴ | R _{DS(on)} | V _{GS} = 10V, I _D = 5A | - | 32 | 45 | mΩ |
| | | V _{GS} = 4.5V, I _D = 3A | - | 38 | 75 | |
| Forward Transconductance ⁴ | g _f | V _{DS} =5V , I _D =5A | - | 12 | - | S |
| Dynamic Characteristics⁵ | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} = 15V, V _{GS} = 0V, f = 1MHz | - | 2420 | - | pF |
| Output Capacitance | C _{oss} | | - | 99 | - | |
| Reverse Transfer Capacitance | C _{rss} | | - | 84 | - | |
| Gate Resistance | R _g | f = 1MHz | - | 1.3 | - | Ω |
| Switching Characteristics⁵ | | | | | | |
| Total Gate Charge | Q _g | V _{GS} = 10V, V _{DS} = 50V, I _D =5A | - | 40.6 | - | nC |
| Gate-Source Charge | Q _{gs} | | - | 8 | - | |
| Gate-Drain Charge | Q _{gd} | | - | 6.7 | - | |
| Turn-On Delay Time | t _{d(on)} | V _{GS} =10V, V _{DD} =50V, R _G = 3Ω, I _D = 5A | - | 8.7 | - | ns |
| Rise Time | t _r | | - | 41 | - | |
| Turn-Off Delay Time | t _{d(off)} | | - | 40 | - | |
| Fall Time | t _f | | - | 32 | - | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Diode Forward Voltage ⁴ | V _{SD} | I _S = 1A, V _{GS} = 0V | - | - | 1.2 | V |
| Continuous Source Current | T _C =25°C | I _S | - | - | 30 | A |

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=8A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

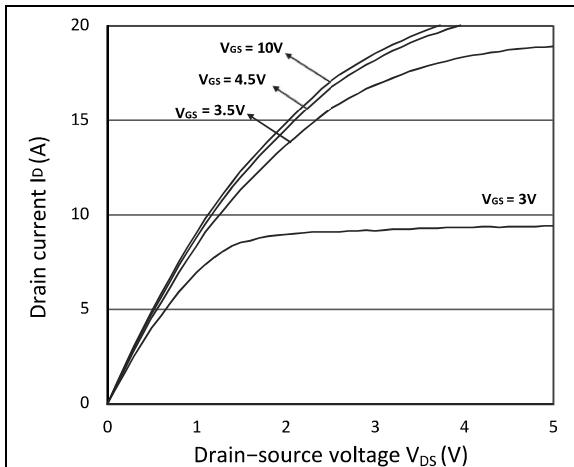


Figure 1. Output Characteristics

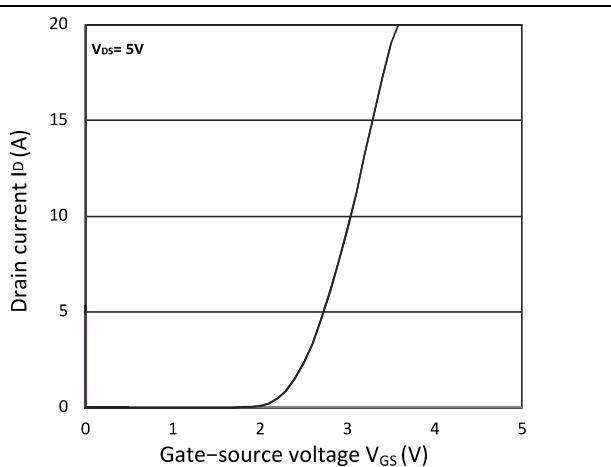


Figure 2. Transfer Characteristics

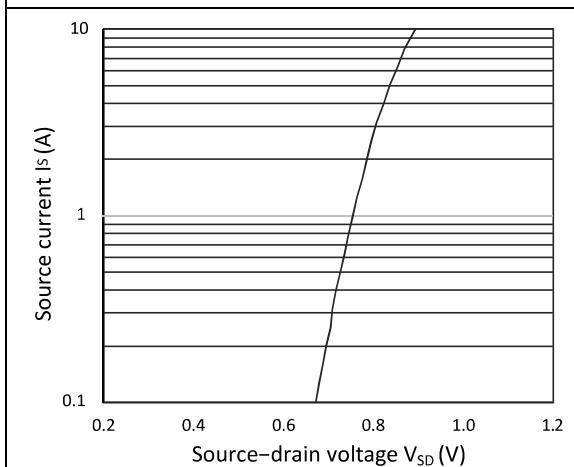


Figure 3. Forward Characteristics of Reverse

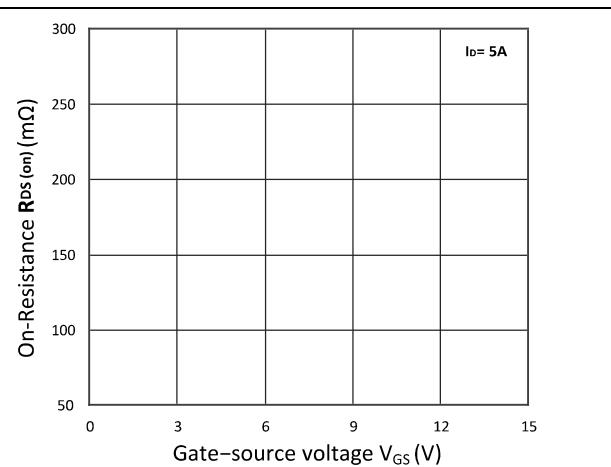


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

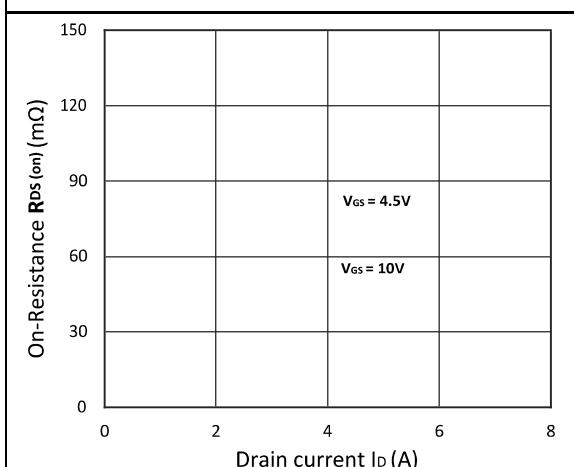


Figure 5. $R_{DS(ON)}$ vs. I_D

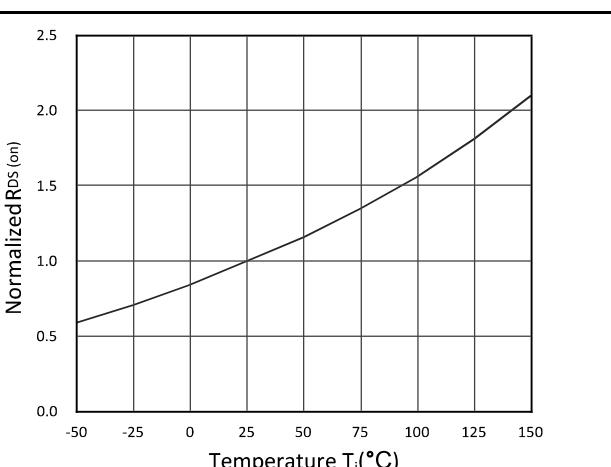
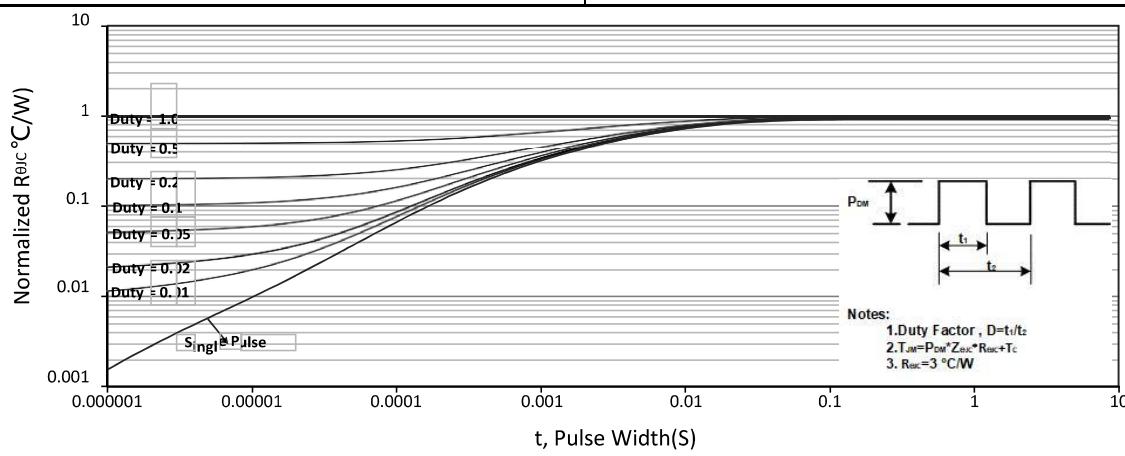
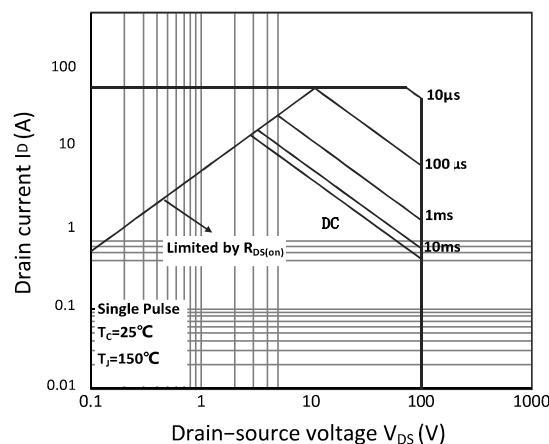
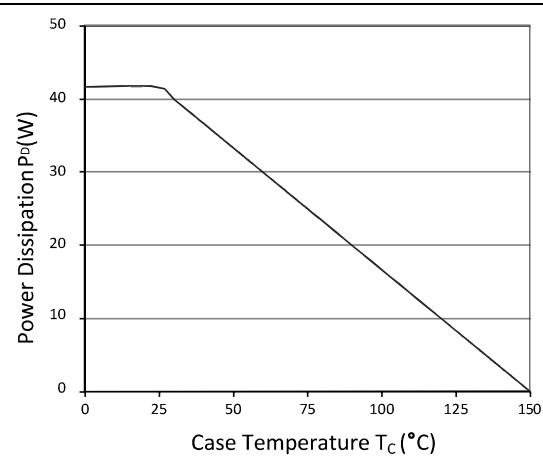
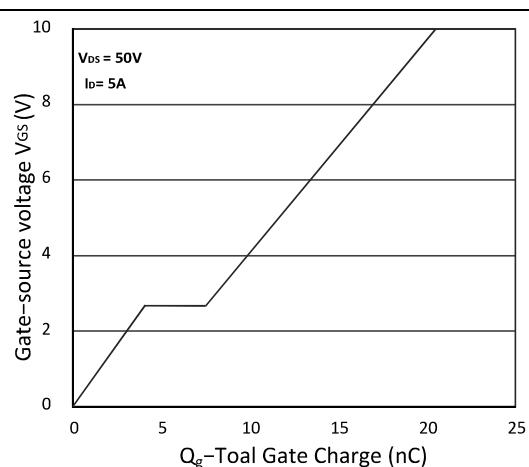
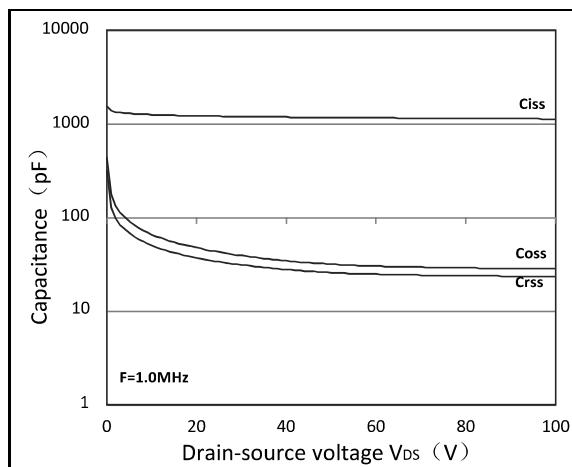
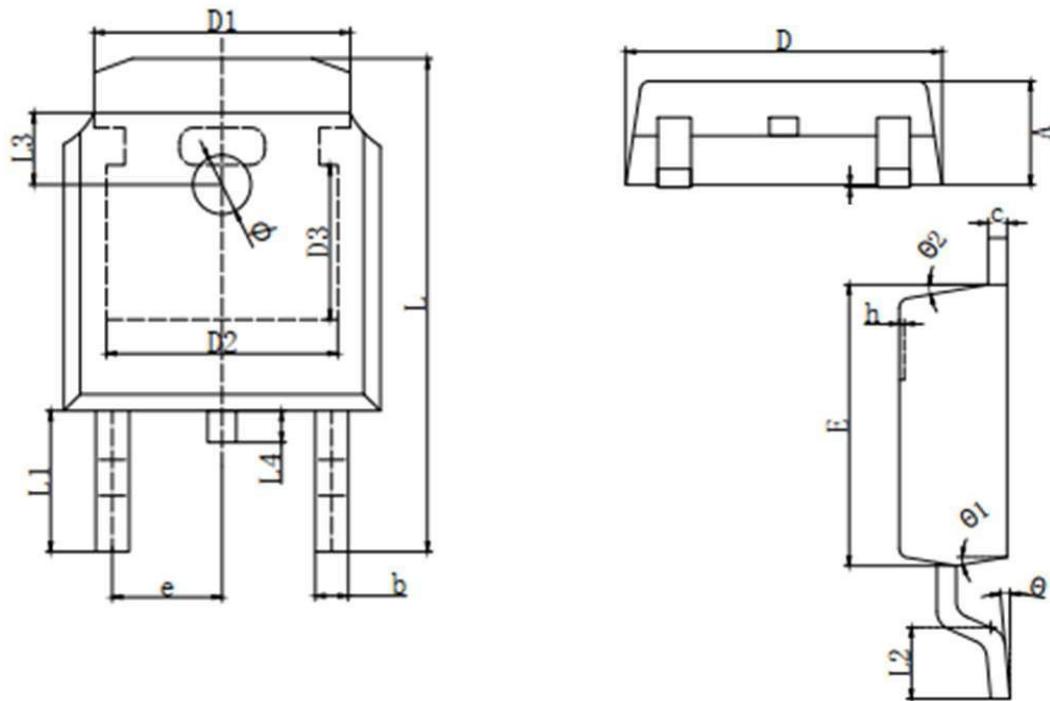


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature



TO-252 Package outline



| SYMBOL | MILLIMETER | | SYMBOL | MILLIMETER | |
|--------|------------|-------|---------|------------|-------|
| | MIN | MAX | | MIN | MAX |
| A | 2.200 | 2.400 | h | 0.000 | 0.200 |
| A1 | 0.000 | 0.127 | L | 9.900 | 10.30 |
| b | 0.640 | 0.740 | L1 | 2.888 REF | |
| c | 0.460 | 0.530 | L2 | 1.400 | 1.700 |
| D | 6.500 | 6.700 | L3 | 1.600 REF | |
| D1 | 5.334 REF | | L4 | 0.600 | 1.000 |
| D2 | 4.826 REF | | phi | 1.100 | 1.300 |
| D3 | 3.166 REF | | theta | 0° | 8° |
| E | 6.000 | 6.200 | theta 1 | 9° TYP2 | |
| e | 2.286 TYP | | theta 2 | 9° TYP | |